

Title (en)
DEVICE AND METHOD FOR PROCESSING OF SUBSTRATES

Title (de)
VORRICHTUNG ZUM BEHANDELN VON SUBSTRATEN

Title (fr)
DISPOSITIF ET PROCÉDÉ POUR PROCESSER DES MATERIAUX EN BANDE

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Abstract (en)

[origin: WO2017089423A1] The invention relates to a device for treating substrates using a separating device. The aim of the invention is to create a device for treating substrates, which allows a separation of treated substrates into one or a plurality of waste parts and into at least one panel. The aim of the invention is in particular to create a device for treating substrates, which has improved flexibility. Said aim is achieved in that the separating device (2) comprises a transport cylinder (3) and a break-out cylinder (4) associated with said transport cylinder, and in that the transport cylinder (3) comprises means for fixing an exchangeable packing (5) as well as first and second openings (12, 13) which are, in the event that the packing (5) is fixed, at least partially covered by perforations that can be formed in the packing (5). According to the invention, first air supply means (14) for feeding air to the first openings (12) as well as second air supply means (15) for feeding air to the second openings (13) independently from the supply of the first openings (12) are provided. The first and/or second air supply means (14, 15) can be switched between a suction air supply and a blow air supply.

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